



CHIPS JOINT UNDERTAKING INTERNATIONAL COOPERATION CALLS 2026

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A ONE-OF-A-KIND PARTNERSHIP FOR EUROPE'S CHIPS INDUSTRY



TRI-PARTITE REPRESENTATION



European Union
European Commission

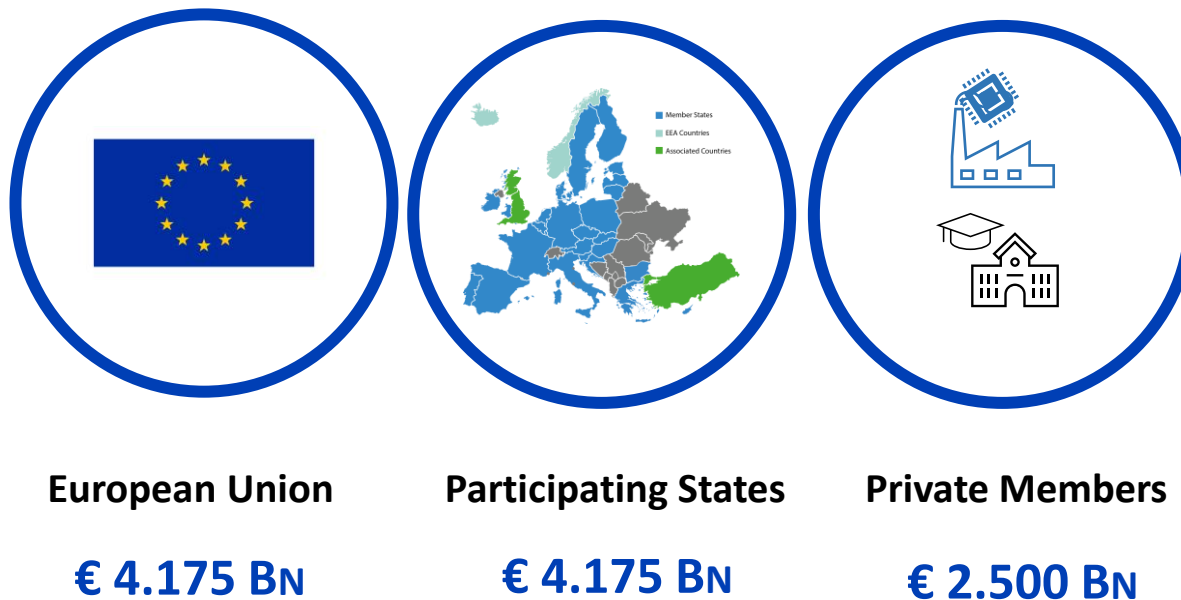


Participating States
Public Authorities



Private Members
Industry Associations

A ONE-OF-A-KIND PARTNERSHIP FOR EU CHIPS INDUSTRY



EU FUNDING PROGRAMMES

Horizon Europe (HE) and Digital Europe Programme (DEP/DIGITAL)

STATE OF PLAY



€ 1.3 BN

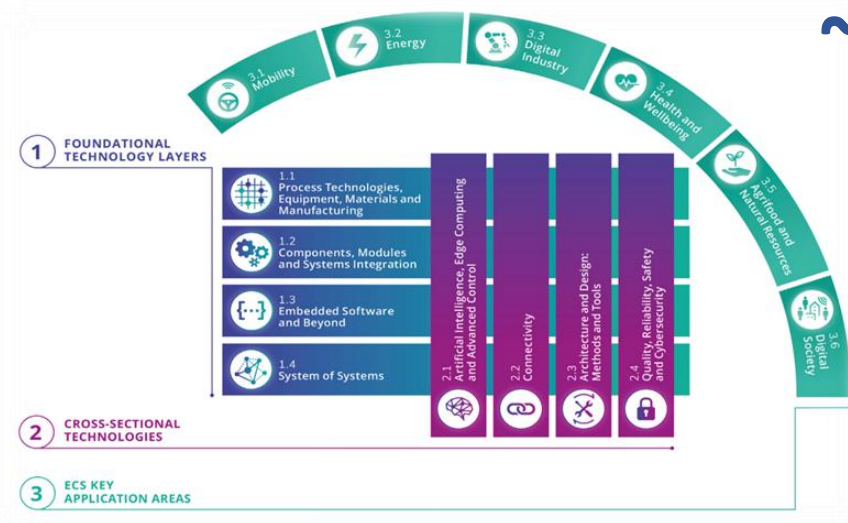
Electronic Components and Systems

€ 2.875 BN

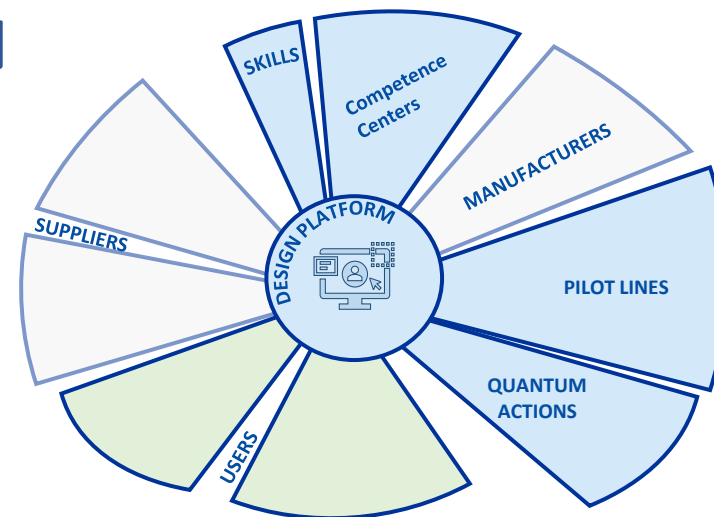
Chips for Europe

~ € 4.175 BN

~92%
Status of
released funding



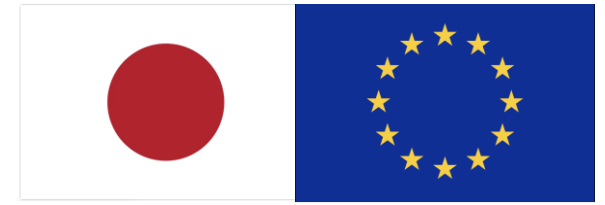
International Cooperation
(ROK, Singapore, Taiwan, India)



International Cooperation (Japan)

EU Chips Act 1.0 - Pillar 1

COOPERATION CALL EU & JAPAN ON SEMICONDUCTORS



Topic: **DIGITAL-JU-Chips-2026-SG-JAPAN (DEP)**

Type of Action	Simple Grant (SG)
Indicative EU budget	5 M€
Expected EU contribution (project)	~3-5 M€
Mode	Co-funded with NFAs 1 stage
Call opens	07 Jul 2026
Submission deadline	24 Sep 2026 17:00h

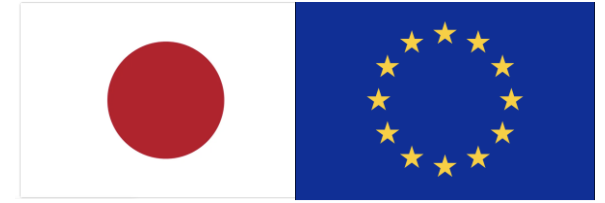
Outcomes

- Advance heterogeneous integration (2.5D/3D, photonics) to enable high-performance, AI-driven semiconductor systems.
- Establish standardised chiplet interfaces to ensure interoperability and a strong European chiplet ecosystem.
- Deliver validated solutions at TRL 5–7 with direct industrial impact and strong EU–Japan collaboration.

Scope

- Develop technologies for chiplet co-design and 2.5D/3D integration, including interconnects, bonding, and photonics processes.
- Foster cross-disciplinary collaboration (materials, manufacturing, AI) to bridge research and industrial deployment.
- Promote international collaboration, notably with Japan, and stakeholder engagement to accelerate innovation and standards.

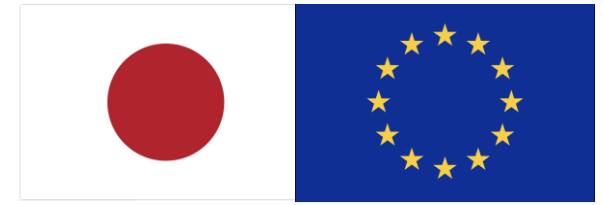
COOPERATION CALL EU & JAPAN ON SEMICONDUCTORS- ELIGIBILITY



Eligibility conditions include the following elements:

- Proposers are expected to work closely with Japanese organisations and are required to describe in their project proposals (DoA-Part B) how they involve their Japanese counterparts and on which activities they collaborate.
- Minimum Consortium composition: 3 eligible legal entities, as beneficiaries, independent from each other (not mandatory they 3 different Member States)
- Japanese organisations shall not be added as associated partners and need to address METI for their participation and funding in the project.
- Proposals should encourage partnerships across industry, academia, and research organizations
- Subject to participation restrictions for the protection of European digital infrastructures, communication and information systems, and related supply chains, as described in Annex 4 to the Multiannual Work Programme 2023-2027 (General Annexes).
- Legal entities that are established in EU Member States, EEA countries (Iceland, Liechtenstein, and Norway), but are controlled from third countries may only participate on the condition that they guarantee the protection of the essential security interests of the Union and the Member States and that they ensure the protection of classified documents information. Where applicable, security guarantees need to be provided after proposal selection.

COOPERATION CALL EU & JAPAN ON SEMICONDUCTORS- REIMBURSEMENT RATE



Reimbursement rates as percentages of the eligible cost according to DEP.

Type of beneficiary	EU Contribution as % of the Eligible Cost according to DEP (*)
For profit organization	50%
SME (for profit SME)	50%
University/Other (not for profit)	50%

(*) beneficiaries may ask for a lower contribution.

ECS International collaboration - Call with Digital Partnership and TTC countries (and Taiwan)

Topic: HORIZON-JU-Chips-2026-3-RIA

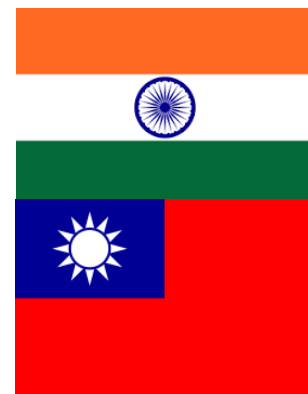
Type of Action	Research and Innovation Action (RIA)
Indicative EU budget	5 M€
Expected EU contribution (project)	~2-2.5 M€
Mode	No co-financing with NFAs 1 stage
Call opens	07 Jul 2026
Submission deadline	16 Sep 2026 17:00h

Outcomes

- Innovative design and integration concepts for neuromorphic computing systems supporting very low energy consumption, connectivity, embedded functions for mobile applications.
- Alternative manufacturing process technologies for semiconductor chips including frontend or backend for heterogenous integration.
- Very advanced packaging solutions aiming heterogeneous integration of multiple functions and materials for applications in communication (RF, mmW or THz), sensing, actuating, power management and active/passive integration.

Scope

- Address research reaching TRL 4 in the design, fabrication process and/or packaging segments of the micro-nano-electronics and integration technologies value chain.
- Focus innovation on materials, physical concepts or device architecture building on neuromorphic or integration technologies.
- Provide a projection of the expected gains and main figures of merit of the proposed approaches.

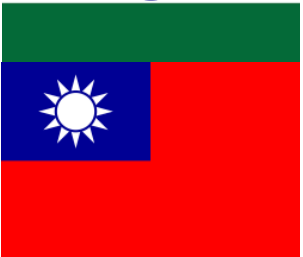


ECS International collaboration - Call with Digital Partnership and TTC countries (and Taiwan)-Eligibility

- Consortia should demonstrate concrete cooperation with organisations from the targeted countries. Such organisations may be included in consortia but should participate as associated partners, without EU funding.
- Minimum Consortium composition: it must include as beneficiaries, three legal entities independent from each other and each established in a different country as follows
 - at least one independent legal entity established in a Member State;
 - and – at least two other independent legal entities, each established in different Member States or Associated Countries
- Participation is limited to legal entities established in EU Member States, EEA Countries (Iceland, Liechtenstein, and Norway), Associated Countries, OECD, Mercosur countries, India, Singapore and Taiwan (see Annex 1 to the General Annexes to the multiannual work programme 2023-2027 “HORIZON Europe conditions applicable to the Chips JU”).

Specific eligibility conditions:

Conditions	Limit
Max Contribution per partner (% of the total EU funding)	30 %
Consortium Size limit	20

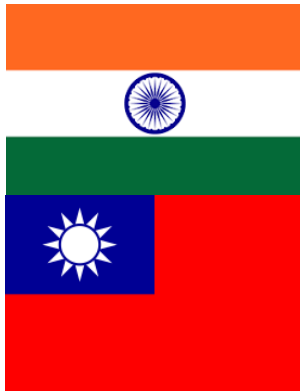


ECS International collaboration - Call with Digital Partnership and TTC countries (and Taiwan)- REIMBURSEMENT

Reimbursement rates as percentages of the eligible cost according to HE.

Type of beneficiary	EU Contribution as % of the Eligible Cost according to HE (*)
For profit organization	100%
SME (for profit SME)	100%
University/Other (not for profit)	100%

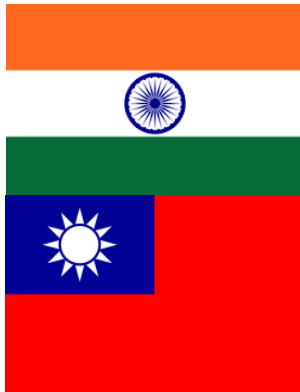
(*) beneficiaries may ask for a lower contribution.



ECS International collaboration - Call with Digital Partnership and TTC countries (and Taiwan)- Third-country contact points

Funding for third-country collaborating participants

- Singapore: National Research foundation, functional mailbox in relation to Horizon
Europe complementary funding is NCP@nrf.gov.sg
- India (work in progress for identification of contact point)
- Taiwan (ITRI)



Thank you!



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[Chips_JU](#)

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Chips Joint Undertaking

